REMARKS

The Office Action mailed August 17, 2005, has been received and reviewed. Claims 1 through 20 are currently pending in the application. Claims 7 through 10 stand rejected. Claims 1 through 6, and 11 through 20 have been allowed. Applicants have amended claims 7 and 10, and respectfully request reconsideration of the application as amended herein.

35 U.S.C. § 102(e) Anticipation Rejections

Anticipation Rejection Based on U.S. Patent No. 6,184,067 to Casper

Claims 7 through 10 stand rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,184,067 to Casper (hereinafter "Casper '067"). Applicants respectfully traverse this rejection, as hereinafter set forth.

A claim is anticipated only if each and every element as set forth in the claim is found, either expressly or inherently described, in a single prior art reference. *Verdegaal Brothers v. Union Oil Co. of California*, 2 USPQ2d 1051, 1053 (Fed. Cir. 1987). The identical invention must be shown in as complete detail as is contained in the claim. *Richardson v. Suzuki Motor Co.*, 9 USPQ2d 1913, 1920 (Fed. Cir. 1989).

Independent claim 7 of the presently claimed invention is directed to a semiconductor die assembly. As amended herein, the semiconductor assembly of claim 7 comprises: a semiconductor die having a plurality of bond pads; a lead frame having a plurality of conductive leads, each conductive lead being electrically coupled at spaced locations on the conductive lead to at least two bond pads of the plurality of bond pads; and *a severance region defined on each conductive lead, the severance region being located and configured to facilitate separation of its associated conductive lead into at least two mutually electrically isolated conductive elements such that each of the at least two mutually electrically isolated conductive elements comprise at least one of the spaced locations to which a bond pad of the at least two bond pads are electrically coupled.*

Applicants submit that Casper '067 fails to describe all of the limitations of the presently claimed invention.

The Examiner cites Casper '067 as disclosing a semiconductor die assembly comprising a semiconductor die having a plurality of bond pads, a lead frame having a plurality of conductive leads, wherein each conductive lead is electrically coupled at spaced locations on the conductive lead to at least two bond pads of the plurality of bond pads. Additionally, with respect to the subject matter previously set forth in claim 10 (i.e., prior to the amendment of claim 10 herein), the Examiner cites Casper '067 as disclosing each conductive lead having a severance region configured to facilitate separation thereof into at least two mutually electrically isolated conductive elements.

The Examiner specifically cites the background section of Casper '067 wherein it states that, after encapsulation of an integrated circuit chip, "the interconnections of the various conductors of the lead frame are removed to leave independent, electrically isolated leads." (Col. 1, lines 25-30). However, this statement is clearly directed to the well known practice of excising of the leads (and possible other lead frame components) from the outer frame portions and tie bars of a lead frame. Such a statement clearly does not describe a lead having a severance region, wherein *the severance region being located and configured to facilitate separation of its associated conductive lead into at least two mutually electrically isolated conductive elements such that each of the at least two mutually electrically isolated conductive elements comprise at least one of the spaced locations to which a bond pad of the at least two bond pads are electrically coupled* as required by claim 7 of the presently claimed invention.

As such, Applicants submit that claim 7 is clearly allowable over Casper '067. Applicants further submit that claims 8 through 10 are also allowable as being dependent from an allowable base claim, as well as for the additional patentable subject matter introduced thereby.

With respect to claim 10, as amended herein, Applicants submit that Casper '067 fails to describe a severance region in each conductive lead that includes at least one notch formed in a surface thereof.

Applicants, therefore, respectfully request reconsideration and allowance of claims 7 through 10.

Anticipation Rejection Based on U.S. Patent No. 6,587,892 to Casper

Claims 7 through 10 stand rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 6,587,892 to Casper (hereinafter "Casper '892"). Applicants respectfully traverse this rejection, as hereinafter set forth.

Independent claim 7 of the presently claimed invention is directed to a semiconductor die assembly. As amended herein, the semiconductor assembly of claim 7 comprises: a semiconductor die having a plurality of bond pads; a lead frame having a plurality of conductive leads, each conductive lead being electrically coupled at spaced locations on the conductive lead to at least two bond pads of the plurality of bond pads; and *a severance region defined on each conductive lead, the severance region being located and configured to facilitate separation of its associated conductive lead into at least two mutually electrically isolated conductive elements such that each of the at least two mutually electrically isolated conductive elements comprise at least one of the spaced locations to which a bond pad of the at least two bond pads are electrically coupled.*

Applicants submit that Casper '892 fails to describe all of the limitations of the presently claimed invention.

The Examiner cites Casper '892 as disclosing a semiconductor die assembly comprising a semiconductor die having a plurality of bond pads, a lead frame having a plurality of conductive leads, wherein each conductive lead is electrically coupled at spaced locations on the conductive lead to at least two bond pads of the plurality of bond pads. Additionally, with respect to the subject matter previously set forth in claim 10 (i.e., prior to the amendment of claim 10 herein), the Examiner cites Casper '892 as disclosing each conductive lead having a severance region configured to facilitate separation thereof into at least two mutually electrically isolated conductive elements.

The Examiner specifically cites the background section of Casper '892 wherein it states that, after encapsulation of an integrated circuit chip, "the interconnections of the various conductors of the lead frame are removed to leave independent, electrically isolated leads." (Col. 1, lines 25-30). However, this statement is clearly directed to the well known practice of excising of the leads (and possible other lead frame components) from the outer frame portions

and tie bars of a lead frame. Such a statement clearly does not describe a lead having a severance region, wherein *the severance region being located and configured to facilitate separation of its associated conductive lead into at least two mutually electrically isolated conductive elements such that each of the at least two mutually electrically isolated conductive elements comprise at least one of the spaced locations to which a bond pad of the at least two bond pads are electrically coupled* as required by claim 7 of the presently claimed invention.

As such, Applicants submit that claim 7 is clearly allowable over Casper '892. Applicants further submit that claims 8 through 10 are also allowable as being dependent from an allowable base claim, as well as for the additional patentable subject matter introduced thereby.

With respect to claim 10, as amended herein, Applicants submit that Casper '892 fails to describe a severance region in each conductive lead that includes at least one notch formed in a surface thereof.

Applicants, therefore, respectfully request reconsideration and allowance of claims 7 through 10.

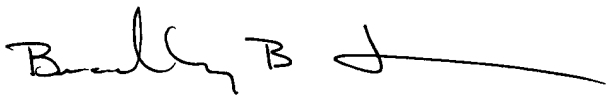
ENTRY OF AMENDMENTS

The amendments to claims 7 and 10 above should be entered by the Examiner because the amendments are supported by the as-filed specification and drawings and do not add any new matter to the application. Further, the amendments do not raise new issues or require a further search.

CONCLUSION

Claims 1 through 20 are believed to be in condition for allowance, and an early notice thereof is respectfully solicited. Should the Examiner determine that additional issues remain which might be resolved by a telephone conference, the Examiner is respectfully invited to contact Applicants' undersigned attorney.

Respectfully submitted,



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